PCN Number:		20141020001					<b>PCN Dat</b>	te:	10/24/2014	
Title:	Title: BQ24257 Datasheet Specification changes for RISET and RILIM Short and LDO									
Custome	er Contact:	PCN Manager		Phone:	+1(214) 480-6037		Dept:	: Quality Services		
Change						_				
Assembly Site				Design			Wafer Bump Site			
Assembly Process					Data Sheet			Wafer Bump Material		
Assembly Materials				Part number change			Wafer Bump Process			
Mechanical Specific				Test Site			Wafer Fab Site			
Packing/Shipping/		Labeling	Test Pro		cess			Wafer Fab Materials		
						Wafer Fab Process				
PCN Details										
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized following:  1. change RISET-SHORT min spec from 45 to 40  2. change RILIM-SHORT min spec from 65 to 55  3. change LDO typical spec from 4.85 to 4.96 and max spec from 5.04 to 5.25  The datasheet number will be changing.										
Device Family		Change Fror				ange To:				
BQ24257		SL	USE	3G0B		SLUSBG0C				
These changes may be reviewed at the datasheet link provided:										
http://www.ti.com/product/bq24257?qgpn=bq24257										
Reason for Change:										
New PG material										
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive/negative):										
Electrical specification performance changes as indicated above.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
BQ2425	7RGER	BQ24257I	RGE	BQ24257YFFR			BQ2	BQ24257YFFT		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com